

Stannatech[®] 2000

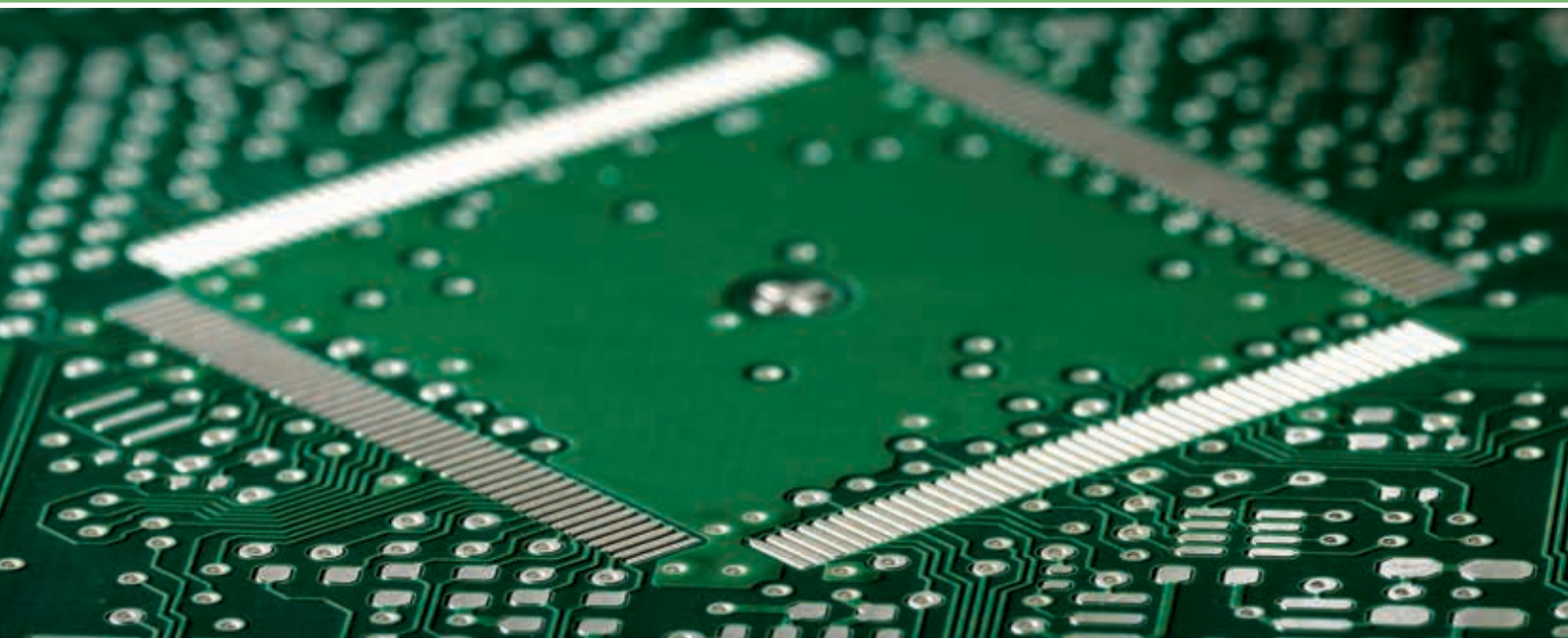
Best proven horizontal immersion tin



Electronics

Final finishing technology

atotech.com



The first choice for automotive applications

10

Million m² production
since release to market

Leading immersion tin process

Stannatech[®] 2000 is the most production represented immersion tin on the market with over 70% market share and >135 customers.

The key to the success of Stannatech[®] 2000 is a system approach that fuses high end equipment with optimized utility chemistry. The optimized chemistry is able to meet deposition rates enabling unique equipment footprints.

Strong OEM ties and a significant customer base guarantees confidence in the capabilities of Stannatech[®] 2000.

MKS' Atotech offers process consistency through performance and auxiliary equipment. Complimentary auxiliary equipment can maximize lifetime and ensure stable process control. Production know-how has led to the development of an anti-whisker additive (AWA). This extensive know-how will also ensure that the process will advance with the technology it serves.

Stannatech[®] 2000: the only choice that combines cost with reliability

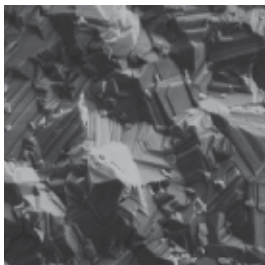


Figure 1-3:
Features and benefits of Stannatech[®] 2000 – applied anti-whisker additive, Horizon[®] equipment and auxiliaries

Advantages of horizontal processing

The Atotech systems approach enables a superior single source process. Aligning equipment and chemistry ensures maximum production benefits.

Reproducible high quality production is guaranteed by the made to measure horizontal transportation system and fluid delivery systems, whilst lifetime and therefore optimum consumption is guaranteed by the auxiliary equipment.

All-in-all a must have process for immersion tin.

Superior corrosion resistance

This self healing finish out performs all other final finishes with regards to highly corrosive environmental testing. This can be accounted for by the metallurgy involved after populating is complete.

Features and benefits

- Equipment and chemistry from a single source
- Planar surface for soldering
- Reliable copper-tin solder joints formed
- Multi solderable at 1.0 μm of tin
- Suitable for press fit technology
- 1 Year storage of PCB
- Cost effective

